

TOREX SEMICONDUCTOR LTD.
Quality Assurance Dept.

Composition Table

Product(Pb-free): XC6230xxxxQR-G
Typical Mass: 80 mg

Part name	Weight(mg)	Material name	Ratio(ppm)	CAS number
Silicon chip	0.881	Silicon	11000	7440-21-3
		- Arsenic	<1	7440-38-2
Leadframe	26.731	Copper	334100	7440-50-8
		Iron	4500	7439-89-6
		Zinc	200	7440-66-6
		Phosphorus	200	7723-14-0
		Silver	2700	7440-22-4
Die attach	0.414	Silver	5200	7440-22-4
		Epoxy resin	700	—
		Phenol resin	100	—
Bonding wire	0.118	Gold	1500	7440-57-5
Resin	44.413	Silica	555200	60676-86-0
		Epoxy resin	49800	—
		Phenol resin	10800	—
		Silica (crystal)	7600	14808-60-7
Plating	1.321	Tin	16500	7440-31-5

* The component composition is based on the information provided by raw material vender.

* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

* Any indication "-" in CAS number means "confidential."